



Full Material Declaration for attached parts list

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Declarations authorised by
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Declaration effective from: 02 January 2014 [Approved: 19 December 2024 07:58 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.29%	Silicon	7440-21-3	100%
			Carbon black	1333-86-4	0.8%
			Silicon Dioxide	7631-86-9	2.5%
			phenolic epoxy resin	61788-97-4	3.7%
Encapsulation	EP (Epoxy resin)	69%	ALUMINUM(III) HYDROXIDE	21645-51-2	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	6%
			Quartz sand	60676-86-0	82%
Inner preparation	Copper alloys	0.13%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.61%	Tin elemental	7440-31-5	100%
			Copper	7440-50-8	0.381%
Leadframe	Nickel and Nickel alloys	28.97%	SILVER, ELEMENTAL	7440-22-4	1.548%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.071%

Attached parts list

Part number	Part name
SOT-23/TO-236_Pb&H-free_(H)_sin.	Diode / Transistor SMD